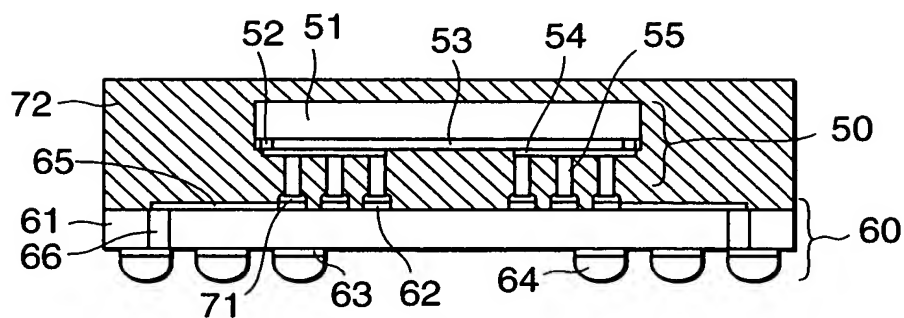
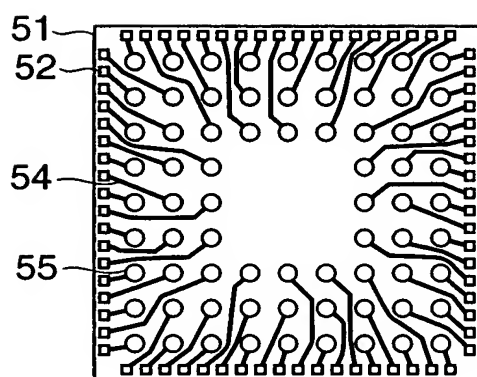


1 / 4



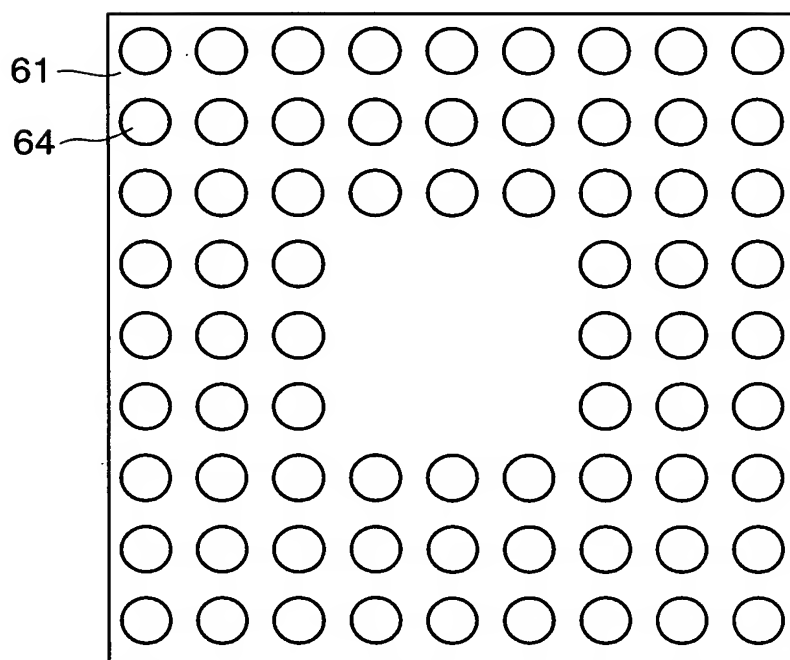
SECTION

FIG. 1A



PLAN OF SEMICONDUCTOR CHIP

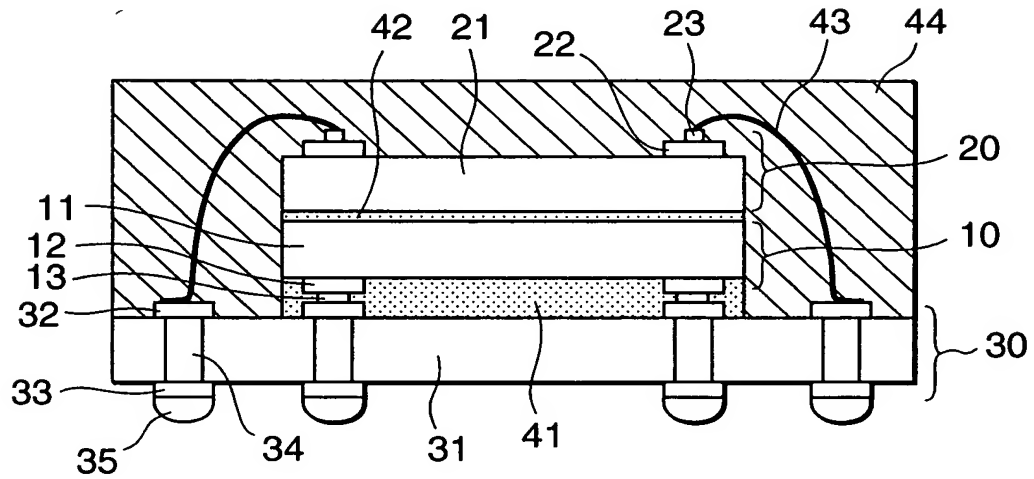
FIG. 1B



SEMICONDUCTOR DEVICE OF FIRST EMBODIMENT
 OF THE PRESENT INVENTION

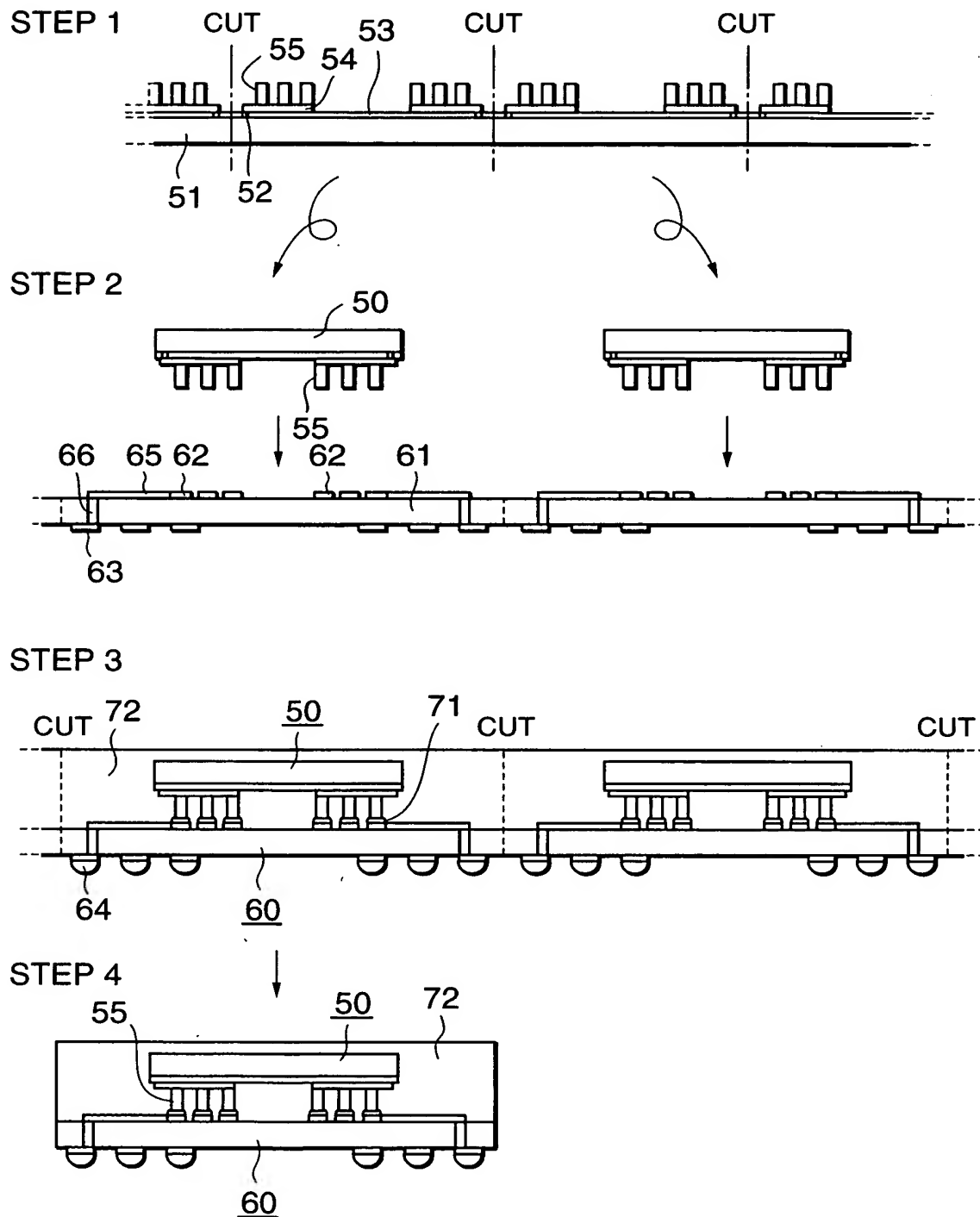
FIG. 1C

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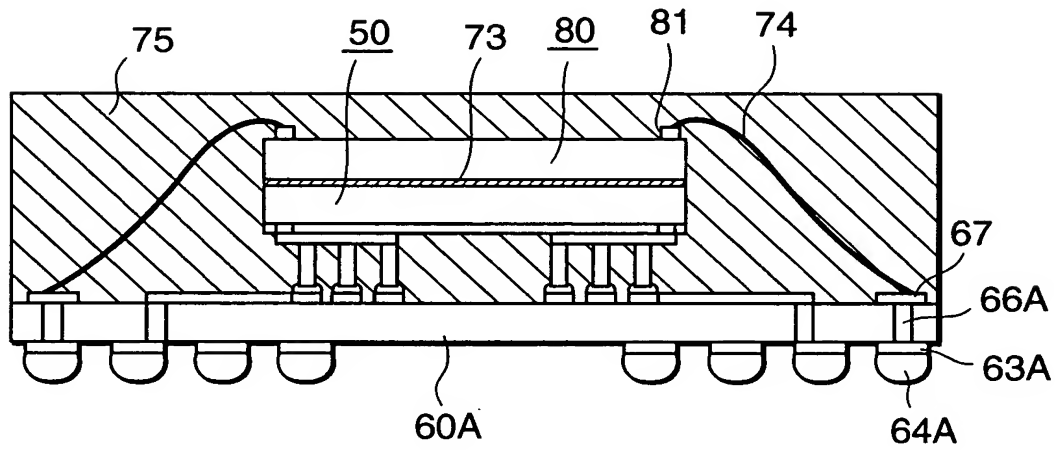
PRIOR-ART SEMICONDUCTOR DEVICE

FIG. 2



MANUFACTURING METHOD OF FIG. 1

FIG. 3



SEMICONDUCTOR DEVICE OF SECOND EMBODIMENT OF
THE PRESENT INVENTION

FIG. 4